IGBT Module

STARPOWER

SEMICONDUCTOR™

GD300HFU120C2S

Molding Type Module

1200V/300A 2 in one-package

General Description

STARPOWER IGBT Power Module provides ultrafast switching speed as well as short circuit ruggedness. It's designed for the applications such as electronic welder and Inductive heating.



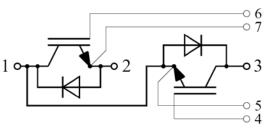
IGBT

Features

- NPT IGBT technology
- 10µs short circuit capability
- Low switching losses
- Rugged with ultrafast performance
- $V_{CE(sat)}$ with positive temperature coefficient
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

Typical Applications

- Switching mode power supplies
- Inductive heating
- Electronic welder



Equivalent Circuit Schematic

1/9

2/17/2011

Symbol	Description	GD300HFU120C2S	Units
V _{CES}	Collector-Emitter Voltage	1200	V
V _{GES}	Gate-Emitter Voltage	±20	V
т	Collector Current @ $T_C=25^{\circ}C$	530	А
I _C	@ T _C =80°C	300	
I _{CM(1)}	Pulsed Collector Current t _p =1ms	600	А
$I_{\rm F}$	Diode Continuous Forward Current	300	А
I _{FM(1)}	Diode Maximum Forward Current	600	А
P _D	Maximum power Dissipation @ T _j =150°C	2119	W
T _{SC}	Γ_{SC} Short Circuit Withstand Time @ T _j =125°C		μs
T _j	Maximum Junction Temperature	150	°C
T _{STG}	Storage Temperature Range	-40 to +125	°C
V _{ISO}	Isolation Voltage RMS,f=50Hz,t=1min	2500	V
Mounting Torque	Power Terminal Screw:M6	2.5 to 5.0	N.m
Mounting Torque	Mounting Screw:M6	3.0 to 6.0	N.m

Absolute Maximum Ratings $T_C=25$ °C unless otherwise noted

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT $T_C=25$ °C unless otherwise noted

Off Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _{(BR)CES}	Collector-Emitter Breakdown Voltage	T _j =25℃	1200			V
I _{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0V,$ $T_j=25^{\circ}C$			5.0	mA
I _{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0V,$ $T_j=25^{\circ}C$			400	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _{GE(th)}	Gate-Emitter Threshold Voltage	$I_C=3.0$ mA, $V_{CE}=V_{GE}$, $T_j=25$ °C	4.4	5.2	6.0	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I_{C} =300A,V _{GE} =15V, T _j =25°C		3.10	3.60	V
		I_{C} =300A, V_{GE} =15V, T_{j} =125 °C	3.45		v	

©2011 STARPOWER Semiconductor Ltd.

2/17/2011

Rev.B

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
t _{d(on)}	Turn-On Delay Time			662		ns
t _r	Rise Time			142		ns
t _{d(off)}	Turn-Off Delay Time			633		ns
t _f	Fall Time	$-V_{CC}=600V,I_{C}=300A,$		117		ns
Eon	Turn-On Switching Loss	$- R_{G} = 3.3\Omega, V_{GE} = \pm 15 V,$ L=200nH, T _j =25 °C		19.7		mJ
E _{off}	Turn-Off Switching Loss			22.4		mJ
t _{d(on)}	Turn-On Delay Time			660		ns
t _r	Rise Time			143		ns
t _{d(off)}	Turn-Off Delay Time			665		ns
t _f	Fall Time	$ V_{CC} = 600 V, I_C = 300 A, R_G = 3.3 \Omega, V_{GE} = \pm 15 V, L = 200 nH, T_j = 125 °C $		137		ns
Eon	Turn-On Switching Loss			24.9		mJ
E _{off}	Turn-Off Switching Loss			28.4		mJ
Cies	Input Capacitance			25.3		nF
C _{oes}	Output Capacitance	V _{CE} =30V,f=1MHz, V _{GE} =0V		2.25		nF
C _{res}	Reverse Transfer Capacitance			0.91		nF
I _{SC}	SC Data	$\begin{array}{c} T_{P} \leqslant 10 \mu s, V_{GE} = 15 \text{ V}, \\ T_{j} = 25 ^{\circ} \text{C}, V_{CC} = 600 \text{ V}, \\ V_{CEM} \leqslant 1200 \text{ V} \end{array}$		2550		А
R _{Gint}	Internal Gate Resistance			1.2		Ω
L _{CE}	Stray Inductance				18	nH
R _{CC'+EE'}	Module Lead Resistance, Terminal To Chip	T _C =25°C		0.32		mΩ

Switching Characteristics

Electrical Characteristics of DIODE $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
V _F	Diode Forward	I -200 A	Tj=25℃		1.82	2.25	V
	Voltage	I _F =300A	T _j =125℃		1.95		V
Qr	Decovered Charge		Tj=25℃		21.5		
	Recovered Charge	I _F =300A,	T _j =125℃		32.4		μC
I _{RM}	Peak Reverse	V_{R} =600 V,	Tj=25℃		178		А
	Recovery Current	di/dt=-2125A/µs,	T _j =125℃		225		
E _{rec}	Reverse Recovery	V _{GE} =-15V	T _j =25℃		10.4		mI
	Energy		T _j =125℃		16.6		mJ

©2011 STARPOWER Semiconductor Ltd.

2/17/2011

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case (per IGBT)		0.059	K/W
$R_{\theta JC}$	Junction-to-Case (per DIODE)		0.107	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.035		K/W
G	Weight of Module	300		g

©2011 STARPOWER Semiconductor Ltd. 2/17/2011 4/9

GD300HFU120C2S

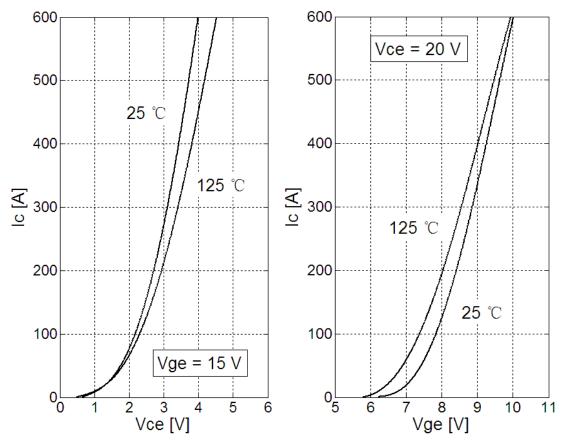
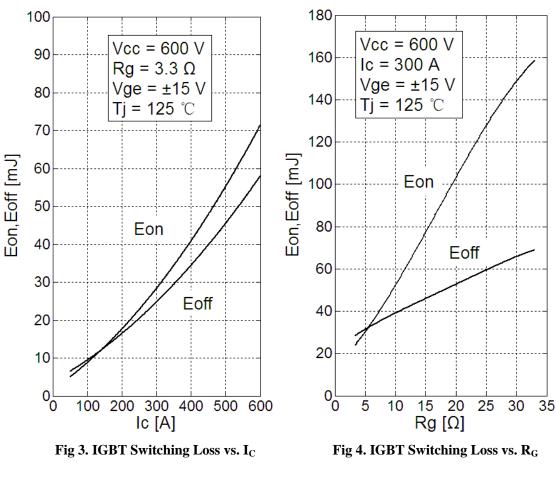
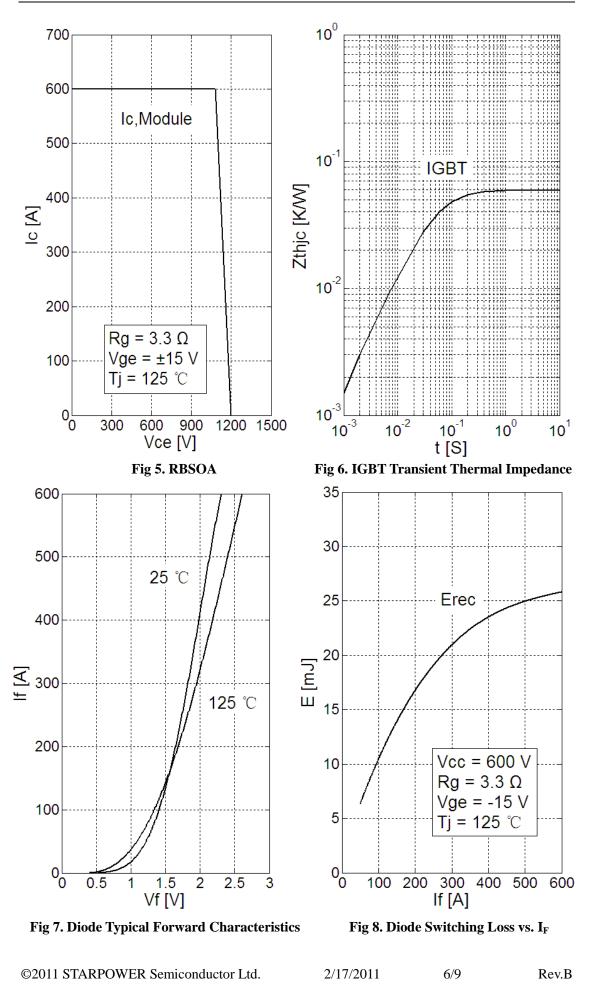


Fig 1. IGBT Typical Output Characteristics Fig 2. IGBT Typical Transfer Characteristics



GD300HFU120C2S

IGBT Module



GD300HFU120C2S

IGBT Module

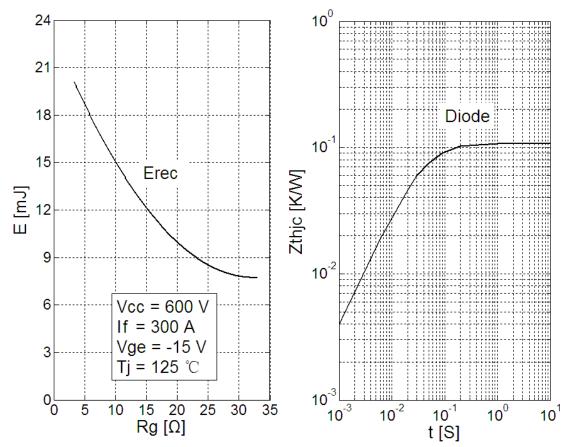
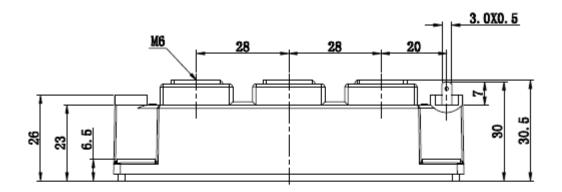


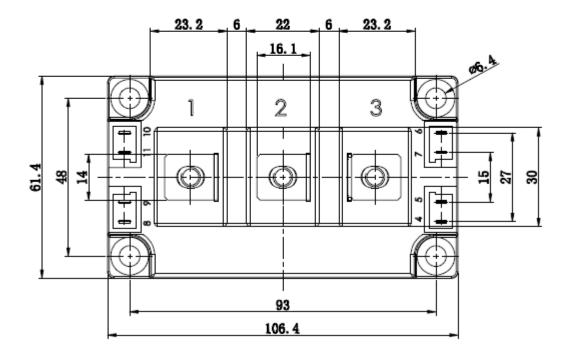
Fig 9. Diode Switching Loss vs. R_G

Fig 10. Diode Transient Thermal Impedance

Package Dimension

Dimensions in Millimeters





Terms and Conditions of Usage

The data contained in this product datasheet is exclusively intended for technically trained staff. You and your technical departments will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to such application.

This product data sheet is describing the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively pursuant the terms and conditions of the supply agreement. There will be no guarantee of any kind for the product and its characteristics.

Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of our product, please contact the sales office, which is responsible for you (see <u>www.powersemi.cc</u>), For those that are specifically interested we may provide application notes.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the Product in aviation applications, in health or live endangering or life support applications, please notify.

If and to the extent necessary, please forward equivalent notices to your customers. Changes of this product data sheet are reserved.

©2011 STARPOWER Semiconductor Ltd. 2/17/2011 9/9 Rev.B

单击下面可查看定价,库存,交付和生命周期等信息

>>STARPOWER(斯达)